

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	2	"US 20070133183"	US-PGPUB; USPAT; USCOCR; DERWENT	OR	ON	2008/03/26 10:05
S2	1	2005-404985.NRAN.	DERWENT	OR	ON	2008/03/26 10:08
S3	4	("6060795 "6127727").PN.	US-PGPUB; USPAT; USCOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 10:14
S5	34	((PETER) near2 (URBACH)).INV.	US-PGPUB; USPAT; USCOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 10:17
S7	58	((WOLFGANG) near2 (FEILER)).INV.	US-PGPUB; USPAT; USCOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 10:17
S9	14	((THOMAS) near2 (RAICA)).INV.	US-PGPUB; USPAT; USCOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 10:18
S11	22	((STEFAN) near2 (HORNUNG)).INV.	US-PGPUB; USPAT; USCOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 10:18
S12	50	(US-20070031137-\$ or US-20070133183-\$). did. or (US-5730869-\$ or US-5944340-\$ or US- 5969942-\$ or US- 5982049-\$ or US- 3605063-\$ or US- 4558549-\$ or US- 4598337-\$ or US- 4836071-\$ or US- 4912601-\$ or US- 5178051-\$ or US- 5217216-\$ or US- 5318820-\$ or US- 5350943-\$ or US- 5398159-\$ or US-	US-PGPUB; USPAT	OR	ON	2008/03/26 10:20

		5429859-\$ or US- 5446626-\$ or US- 5498905-\$ or US- 5753971-\$ or US- 5864482-\$ or US- 6049043-\$ or US- 6050206-\$ or US- 6065857-\$ or US- 6109445-\$ or US- 6158315-\$ or US- 6447898-\$ or US- 6646197-\$).did. or (US- 4332307-\$ or US- 4342177-\$ or US- 4398137-\$ or US- 4407006-\$ or US- 4449769-\$ or US- 4496830-\$ or US- 4504427-\$ or US- 4534671-\$ or US- 4545481-\$ or US- 4800463-\$ or US- 4873508-\$ or US- 4944819-\$ or US- 4956765-\$ or US- 4963876-\$ or US- 4975545-\$ or US- 4977766-\$ or US- 5009090-\$ or US- 5357238-\$ or US- 5363085-\$ or US- 5374399-\$ or US- 5503138-\$ or US- 5513077-\$).did.				
S13	5	"DE 3406528" "DE 4337390" "WO 0127997" "WO 0163671"	US-PCPUB; USPAT; USOCR; FPRS; EPO; JPO; DERVENT	OR	ON	2008/03/26 12:18
S14	2	"4710795".pn.	US-PCPUB; USPAT; USOCR; FPRS; EPO; JPO; DERVENT	OR	ON	2008/03/26 12:21
S15	2	"6697257".pn.	US-PCPUB; USPAT; USOCR; FPRS; EPO; JPO; DERVENT	OR	ON	2008/03/26 12:22
S16	2	"20030142480".pn.	US-PCPUB; USPAT; USOCR; FPRS; EPO; JPO; DERVENT	OR	ON	2008/03/26 12:25

S17	1	2001-318066.NRAN.	DERWENT	OR	ON	2008/03/26 12:31
S18	2789	310/71.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 12:40
S19	118	310/71.ccls. and substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 18:27
S20	203	310/71.ccls. and clip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 19:51
S21	472	310/71.ccls. and commutator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 19:51
S22	13	310/71.ccls. and commutator and mosfet	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 19:52
S23	5	310/71.ccls. and (electromagnetic same shield\$3 same bod\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 19:55
S24	2	310/71.ccls. and (electro adj magnetic same shield\$3 same bod \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/26 19:57
S25	0	310/71.ccls. and (nip adj clinch)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/27 19:25
S26	0	310/71.ccls. and (nip with clinch)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/27 19:25

S27	4	(nip adj clinch)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/27 19:28
S29	27	310/71.ccls. and microprocessor	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:03
S30	14	310/71.ccls. and microprocessor and (sensor\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:04
S31	24194	substrate and microprocessor and (sensor\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:33
S32	17469	substrate and microprocessor and (sensor\$3) and electronic	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:37
S33	1833	substrate and microprocessor and (sensor\$3) and electronic and (control adj logic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:48
S34	275	substrate and microprocessor and (sensor\$3) and electronic and (control adj logic) and (shaft)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 16:49
S35	1	310/71.ccls. and (flip adj chip)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:23
S36	3790	(power same electronic) and (flip adj chip)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:25
S37	3438	(power same electronic) and (flip adj chip) and substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:26

S38	2585	(power same electronic) and (flip adj chip) and substrate and (solder\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:26
S39	2438	(power same electronic) and (flip adj chip) and substrate and (solder\$3) and (conduct \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:27
S40	1437	(power with electronic) and (flip adj chip) and substrate and (solder \$3) and (conduct\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:27
S41	192	(power adj electronic) and (flip adj chip) and substrate and (solder \$3) and (conduct\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:27
S42	2	"6724079".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:29
S43	1	310/71.ccls. and (bare adj die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:36
S44	22	S41 and (bare adj die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:37
S45	29	S41 and (MOSFET)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 17:40
S46	9	310/71.ccls. and (extrusion adj coat\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:09
S47	192	(power adj electronic) and (flip adj chip) and substrate and (solder \$3) and (conduct\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:33

S48	0	S47 and commutator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:33
S49	1416	substrate and commutator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:34
S50	193	(electronic adj unit) and commutator	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:36
S51	6	(electronic adj unit) and commutator and substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/03/28 21:36
S52	11	310/71.ccls. and (punch \$3 with metal\$4 with material)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 10:37
S53	3	310/71.ccls. and substrate and (punch\$3 with metal\$4)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 10:40
S54	1	310/71.ccls. and substrate and (encapsulat\$3 with plastic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 10:41
S55	4	310/71.ccls. and substrate and (inject\$3 with mold\$3 with plastic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 10:42
S56	324825	("257".clas. "361".clas.) and substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 13:31
S57	610	("257".clas. "361".clas.) and substrate and (punch with metal)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 13:33

S58	115	("257".clas. "361".clas.) and substrate and (punch with copper)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 13:33
S59	32	("257".clas. "361".clas.) and substrate and (punch with copper) and encapsulat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 13:42
S60	4	("257".clas. "361".clas.) and substrate and (punch with copper) and (encapsulat\$3 with plastic)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 13:42
S62	89	("257".clas. "361".clas.) and substrate and (punch with metal) and (inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:53
S63	0	("257".clas. "361".clas.) and substrate and (punch with copper) and (encapsulat\$3 with inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:56
S64	1328	("257".clas. "361".clas.) and substrate and (encapsulat\$3 with inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:56
S65	968	("257".clas. "361".clas.) and substrate and metal and (encapsulat \$3 with inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:56
S66	715	("257".clas. "361".clas.) and substrate and copper and (encapsulat \$3 with inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:58
S67	22	("257".clas. "361".clas.) and substrate and (punch\$3 with copper) and (encapsulat\$3 with inject\$3 with mold\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2008/10/30 17:58
S68	5	310/68R.cds. and (punch\$3 with grid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2009/05/14 18:11

S69	8	310/71.ccls. and (punch \$3 with grid)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT	OR	ON	2009/05/14 18:13
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